

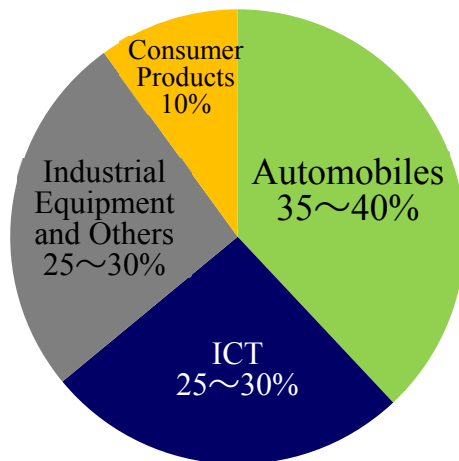
# Strategy of Priority Five Businesses

**Inductive Devices**  
**High Frequency Components**  
**Piezoelectric Material Products**  
Rechargeable Batteries  
HDD Heads

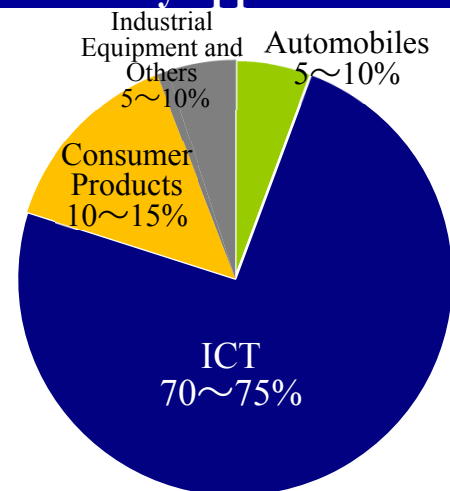
**Executive Vice President**  
**Hiroyuki Uemura**

# Inductive Devices

## Inductive device sales by applications



## Metal power inductor sales by applications



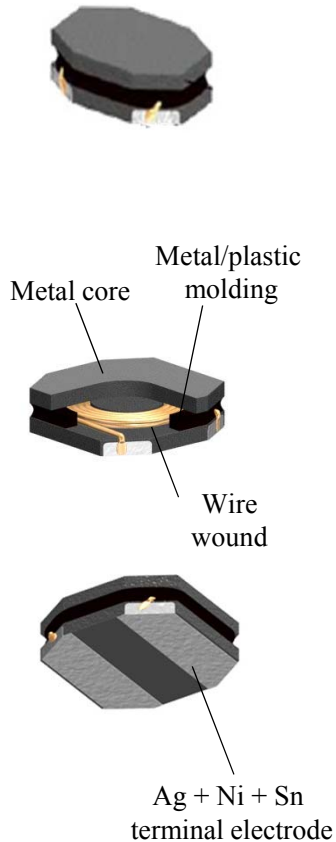
## 【 Metal inductor production engineering 】

Engineering	Feature	Characteristic		Major product	Competitor
Wire wound	Large current High reliability	Size	2016~1717	VLS CLF SPM	Company C Company S Company T Company V
		Frequency	~10MHz		
		Current	3~10A		
Thin film (plating)	Large current Small/Low profile	Size	1608 height 0.5mm	TFM	Company S
		Frequency	~10MHz		
		Current	2~6A		
Multilayer	Small Low profile Suitable for high-frequency applications	Size	1005~2016	MLS MLP	Company T
		Frequency	~200MHz		
		Current	~2A		

# Features of metal power inductors

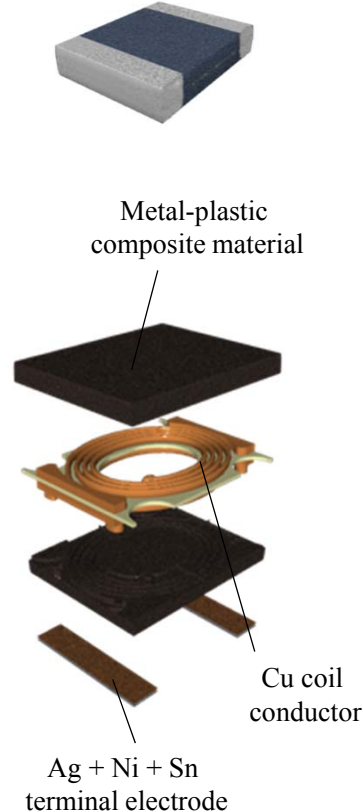
## Metal Wire Wound VLS-HB Series

**Large current**  
**Broad inductance range**



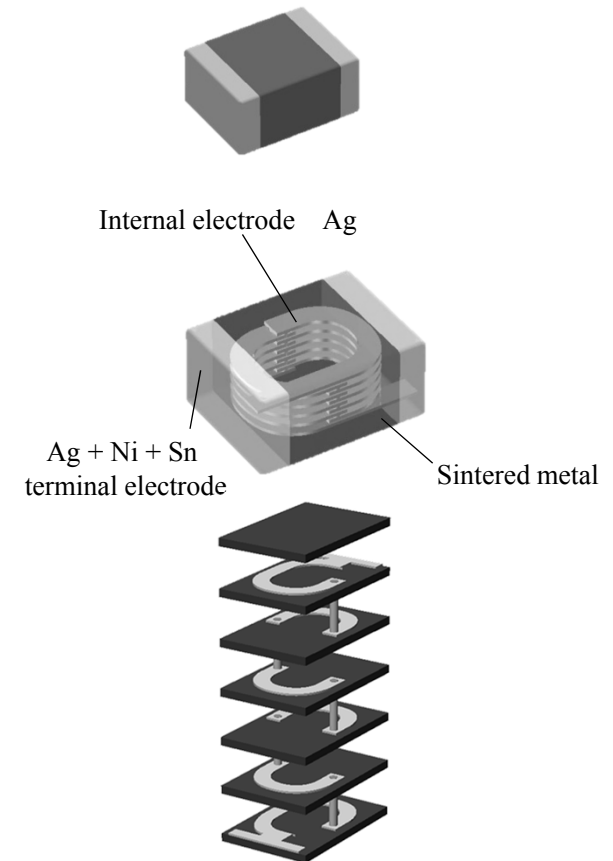
## Metal Thin Film (plating) TFM Series

**Small/Low profile**  
**Large current**



## Metal Multilayer MLS Series

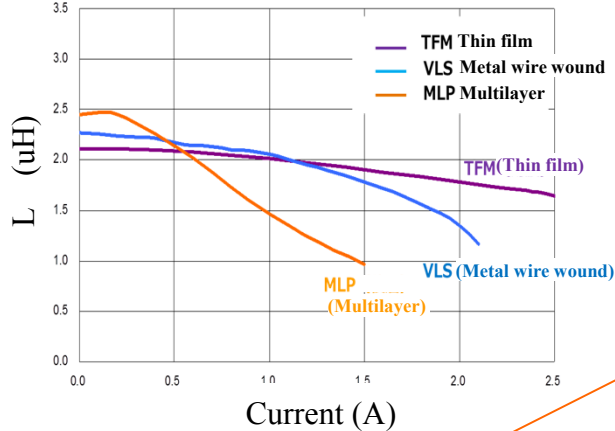
**Small/Low profile**  
**Low loss**



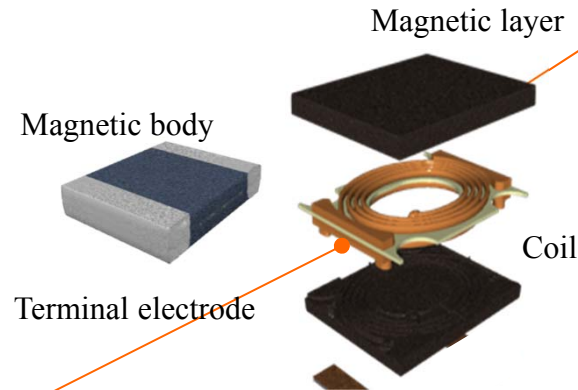
# Structure and features of thin-film metal inductor/TFM

## Structure

Reduced current-dependent characteristic variation  
→ Suitable for large-current applications

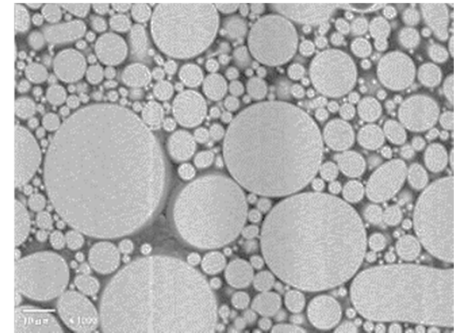


## Structure

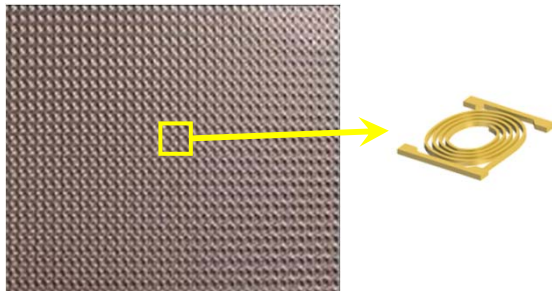


## Magnetic metal material

High-dispersion and high-filling technique used to achieve high  $\mu$

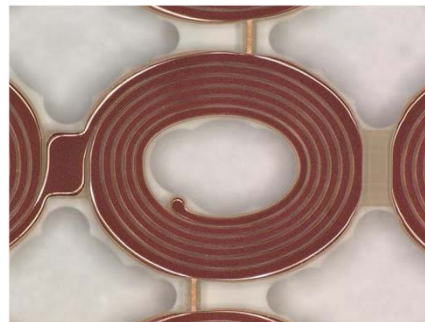


## Coil substrate



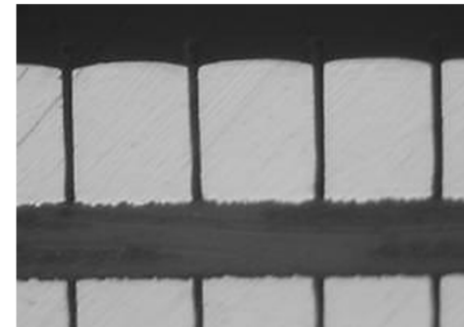
Substrate process to improve production efficiency

## Coil conductor



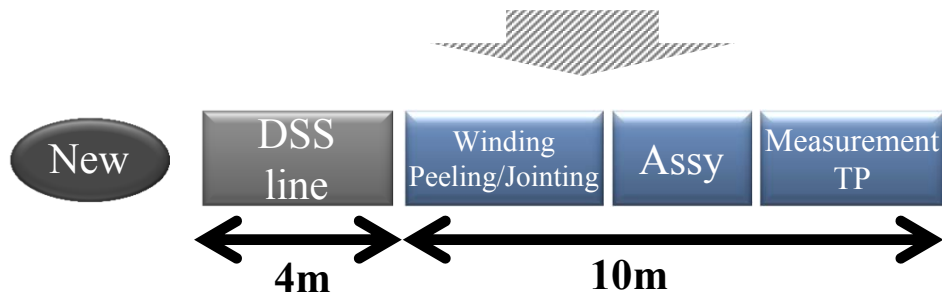
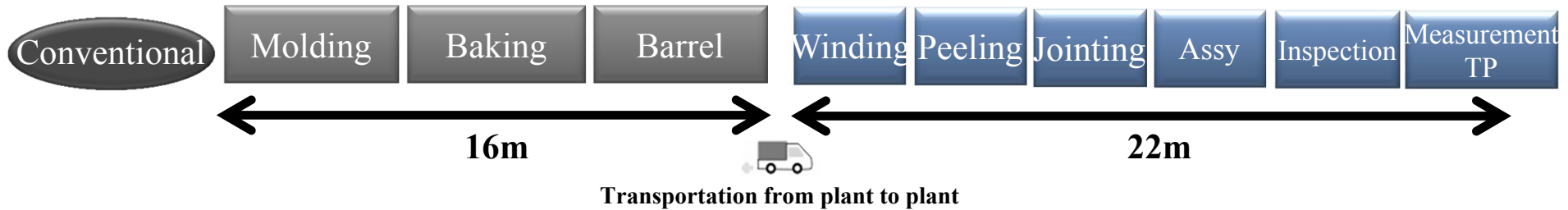
High-density coil conductor formed by micro-patterning

## Coil conductor cross section



High-density winding and low-resistance coil enabled by newly developed high-aspect and high-precision plating technique

# Core & Inductor: Integrated location-free production



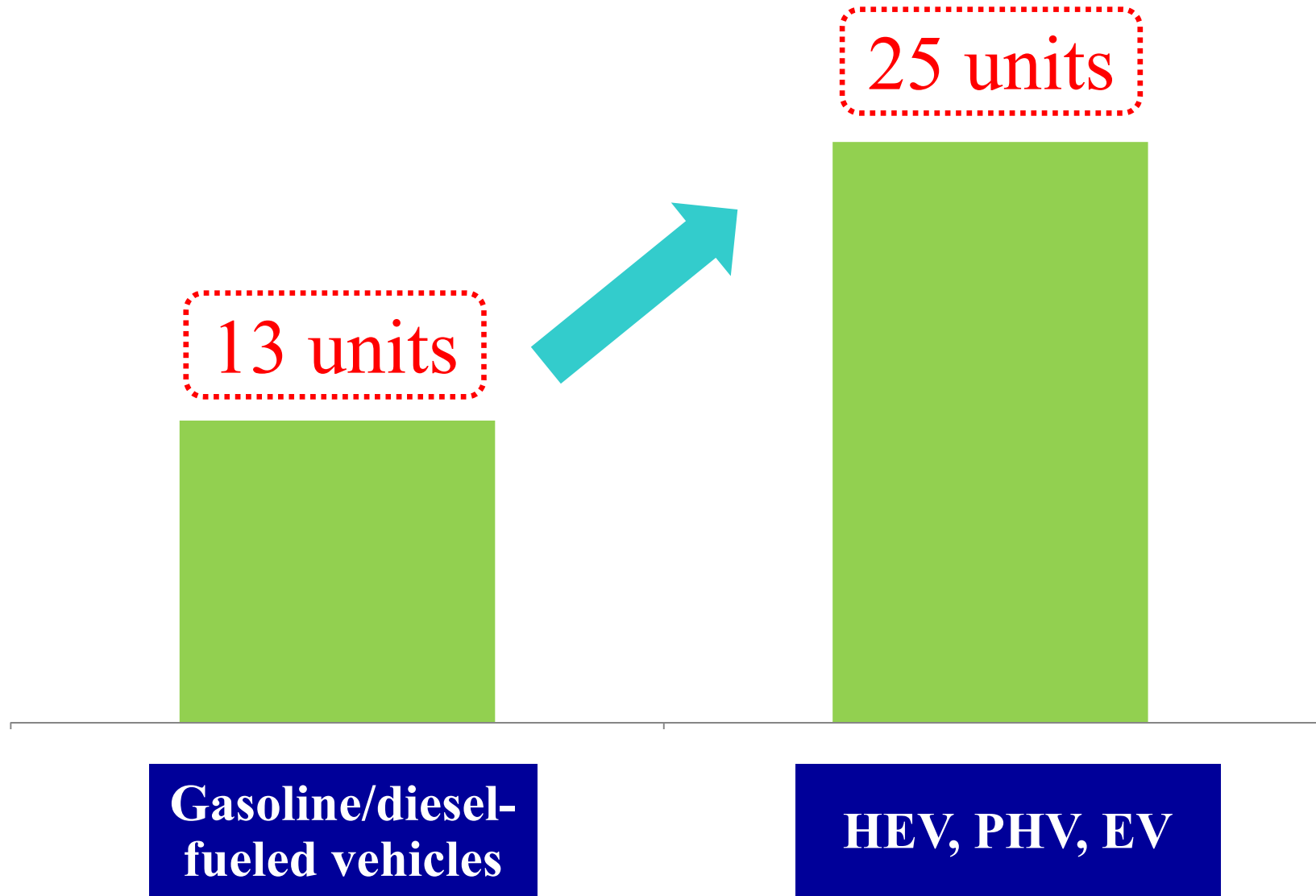
	Reduction rate
Line length	-60~75%
Area	-70~85%
Lead time	-60~75%
Personnel/Line	-70~90%

## Making it location-free

Manufacturing reformed to produce products for high-demand markets

### Advantages

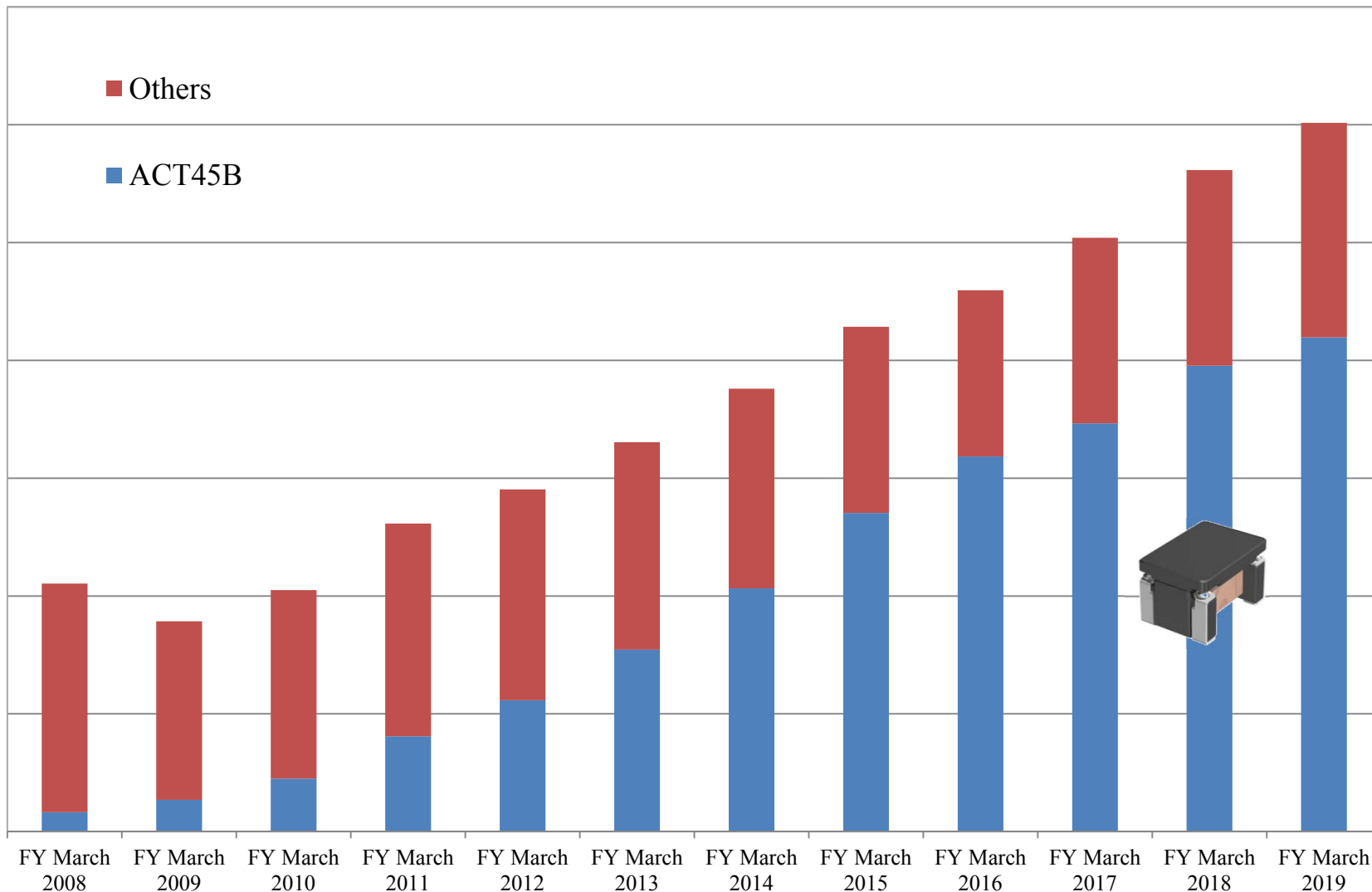
- **Solution to increasing personnel costs in China**  
→ Manufacturing in China to meet domestic demand in China  
Manufacturing of export items conducted outside China  
(Manufacturing might be repatriated to Japan.)
- **Capability to cope with sharp foreign exchange movements**



※TDK's estimation

# CAN filter sales trends

Quantity



## ① Enhancing metal inductors

Lineup comprising a full range of thin-film, multilayer and wire wound inductors, notably with an increased line of TDK's flagship thin-film inductors

## ② Comprehensive application of integrated location-free production lines

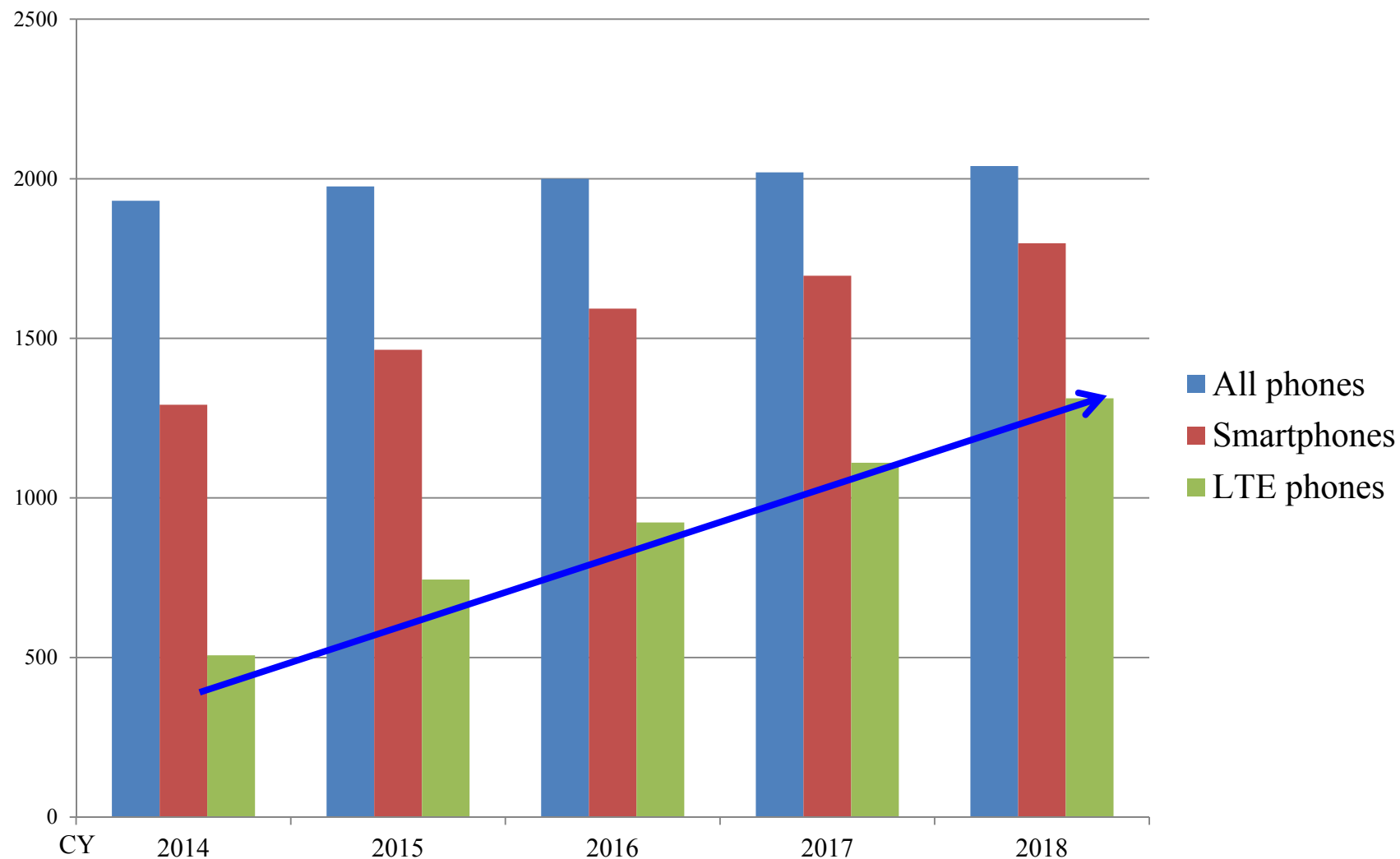
Relocating part of manufacturing sites from China to Japan to be considered according to foreign exchange movements

## ③ Strengthening collaborations with IC manufacturers

# High Frequency Components

# Mobile phone market overview

Phones 【M pcs】

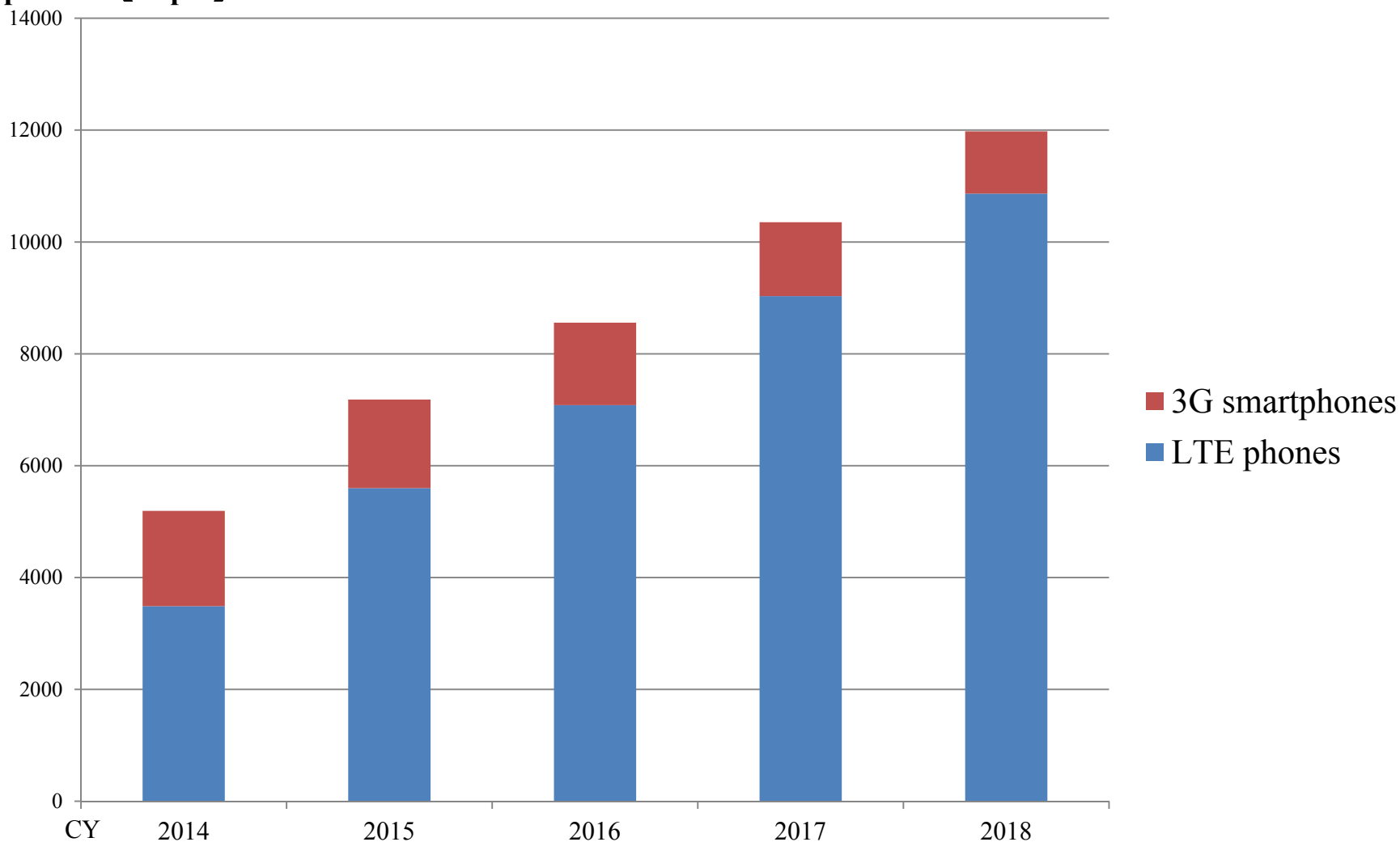


※TDK's estimation

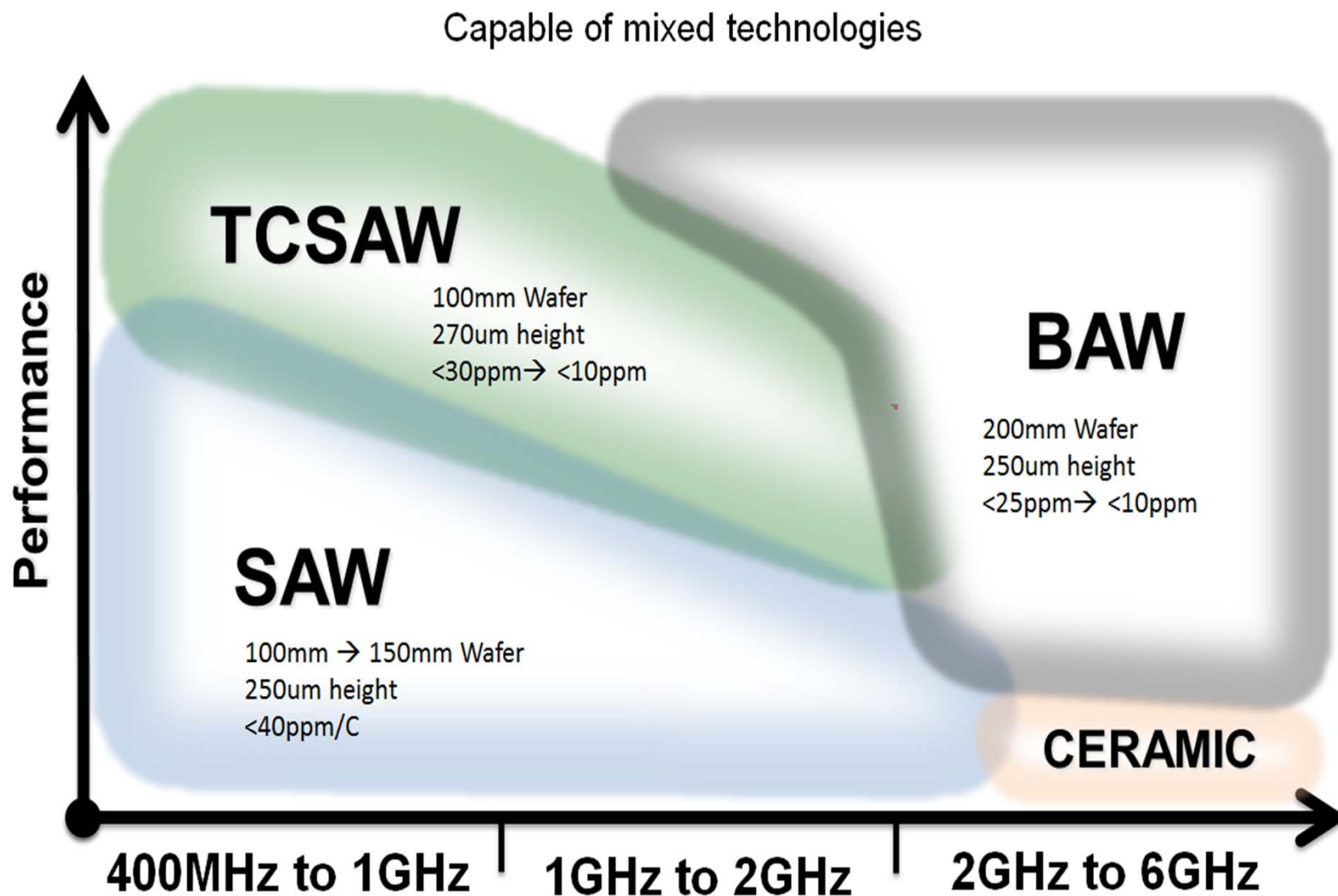
# Duplexer market expansion by the use of LTE



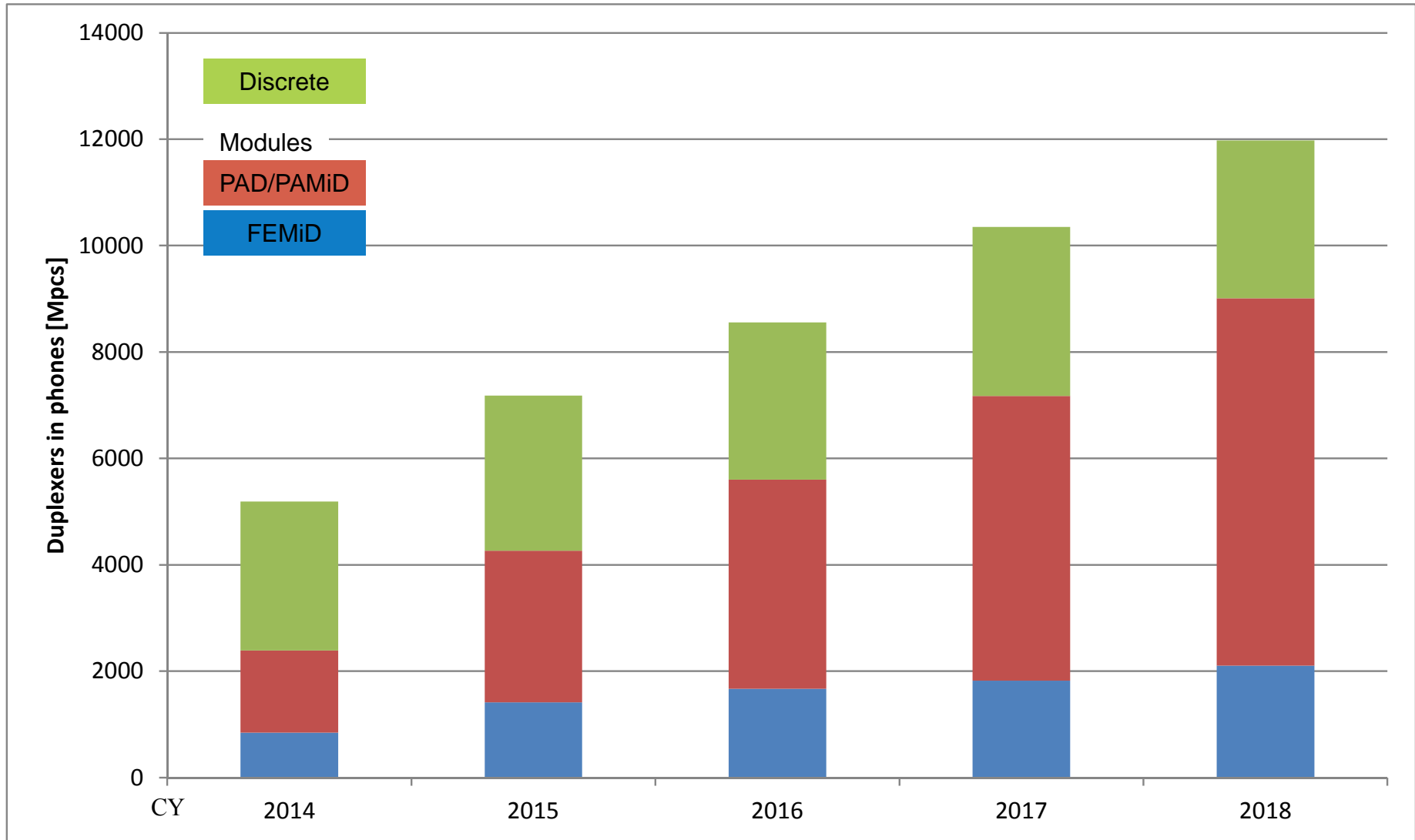
Duplexers 【M pcs】




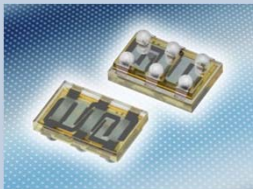
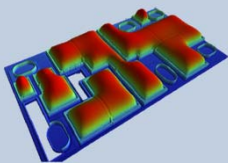
※TDK's estimation



# Discrete components versus modules in duplexer market



※TDK's estimation

Packaging Technology	Feature	Use	Height
<b>CSSP</b> 	General-purpose package for discrete components (in volume production)	Mobile phones Telematics	0.6 mm
<b>DSSP</b> 	Small package for SAW (in volume production)	Modules for mobile phones	0.4 mm
<b>TFAP</b> 	Next-generation wafer-level package for SAW and BAW (in preparation for volume production)	Modules for next-generation mobile phones	0.25 mm

## ① Making filters higher value-added and suitable for modules

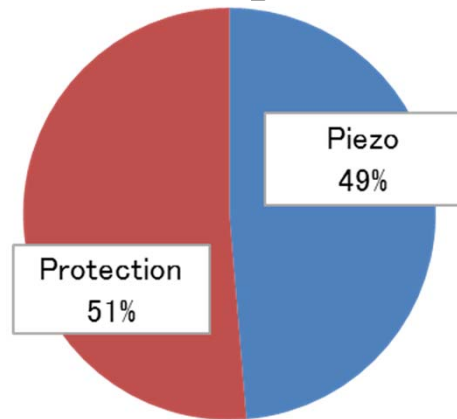
- SAW, TCSAW and BAW filters to cover the entire range
- New packages for shifting toward smaller size and lower profile and for simplifying the subsequent process

## ② Strengthen relationships with IC manufacturers

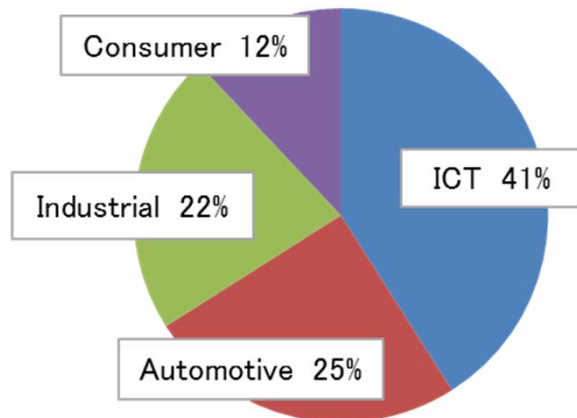
- Providing solutions drawing on reference design-in
- Collaboration with PA manufacturers to meet PAD/PAMiD market needs

# Piezoelectric Material Products

## 【Sales breakdown】



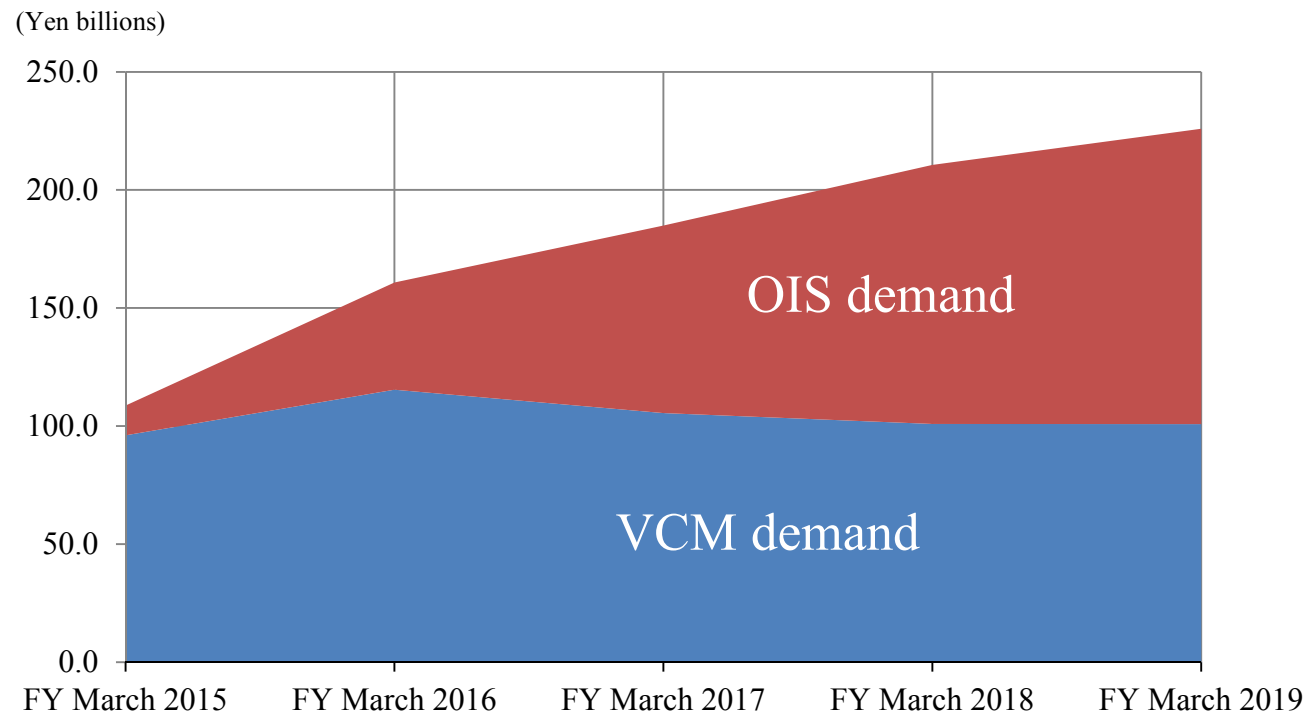
## 【Sales by applications】



Application	Main Products
ICT	Camera module actuators Surge arresters Chip components (varistors and NTCs)
Automobiles	Piezo injectors Chip components (varistors and NTCs) PTC
Industrial Equipment and Others	Disc varistors PTC Chip components (varistors and NTCs)
Consumer Products	Piezo actuators PTC Disc varistors

- Growth in ICT market principally with camera module actuators
- Ceramic protection components cover all areas of application

## Demand for Camera Module Actuators



※TDK's estimation

Demand for high-performance OIS camera module actuators is expected to grow from now on. TDK's OIS sales will be expanded to achieve overall business growth.

- ① **Growth of OIS camera module actuator products**
- ② **Promoting development of Ceralink for the automotive industry**
- ③ **TDK has the largest share of the market for ceramic protection components (arresters, varistors, PTCs and chip components) and earns profits stably from this market**

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